

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH47N60_F133	FCH47N60_F133	TO-247	-	-	30
FCA47N60	FCA47N60	TO-3PN	-	-	30
FCA47N60	FCA47N60_F109	TO-3PN	-	-	30

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA, T _J = 25°C	600	--	--	V
		V _{GS} = 0V, I _D = 250μA, T _J = 150°C	--	650	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	--	0.6	--	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	V _{GS} = 0V, I _D = 47A	--	700	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600V, V _{GS} = 0V V _{DS} = 480V, T _C = 125°C	-- --	-- --	1 10	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	3.0	--	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 23.5A	--	0.058	0.07	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 23.5A (Note 4)	--	40	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	5900	8000	pF
C _{oss}	Output Capacitance		--	3200	4200	pF
C _{rss}	Reverse Transfer Capacitance		--	250	--	pF
C _{oss}	Output Capacitance	V _{DS} = 480V, V _{GS} = 0V, f = 1.0MHz	--	160	--	pF
C _{oss eff.}	Effective Output Capacitance	V _{DS} = 0V to 400V, V _{GS} = 0V	--	420	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 300V, I _D = 47A R _G = 25Ω (Note 4, 5)	--	185	430	ns
t _r	Turn-On Rise Time		--	210	450	ns
t _{d(off)}	Turn-Off Delay Time		--	520	1100	ns
t _f	Turn-Off Fall Time		--	75	160	ns
Q _g	Total Gate Charge	V _{DS} = 480V, I _D = 47A V _{GS} = 10V (Note 4, 5)	--	210	270	nC
Q _{gs}	Gate-Source Charge		--	38	--	nC
Q _{gd}	Gate-Drain Charge		--	110	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	47	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	141	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 47A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 47A	--	590	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100A/μs (Note 4)	--	25	--	μC

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS} = 18A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C
3. I_{SD} ≤ 47A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C
4. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

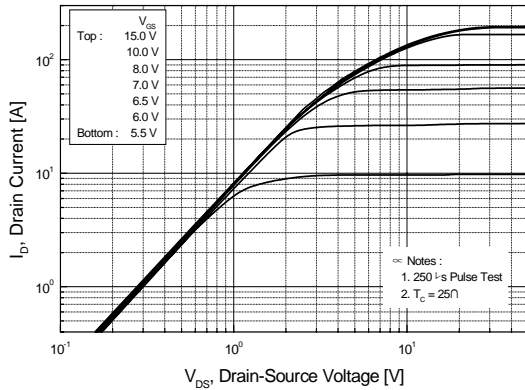


Figure 2. Transfer Characteristics

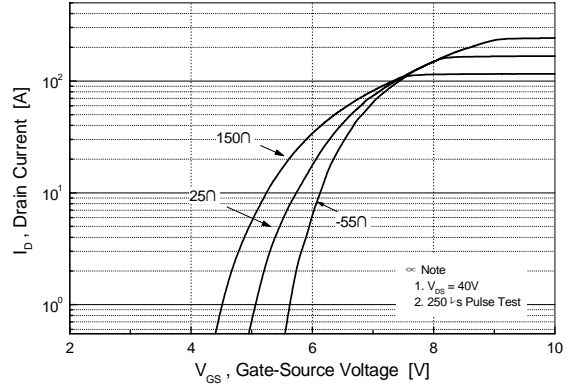


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

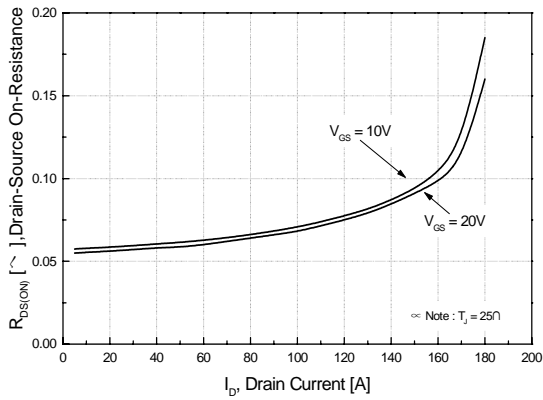


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

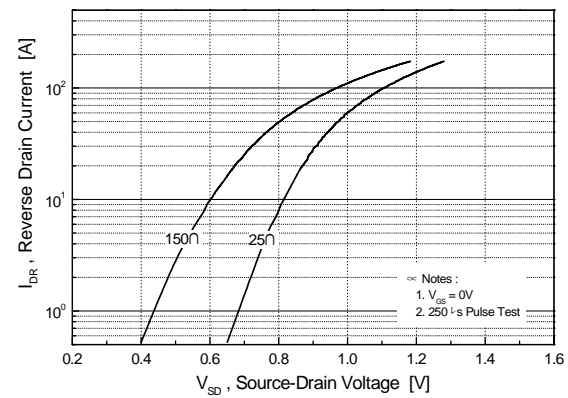


Figure 5. Capacitance Characteristics

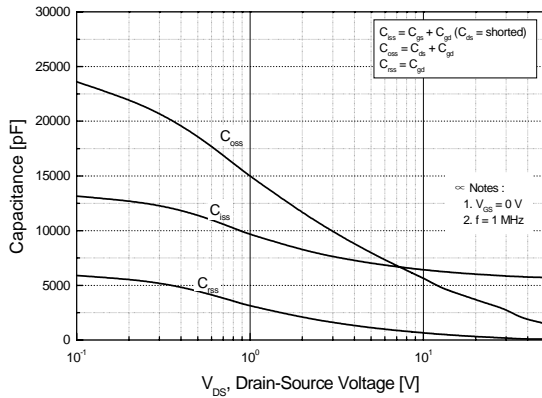
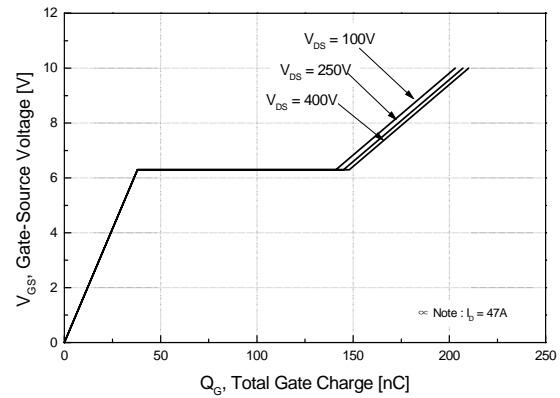


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

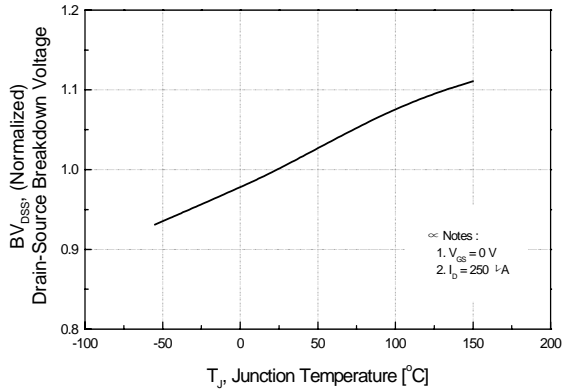


Figure 8. On-Resistance Variation vs. Temperature

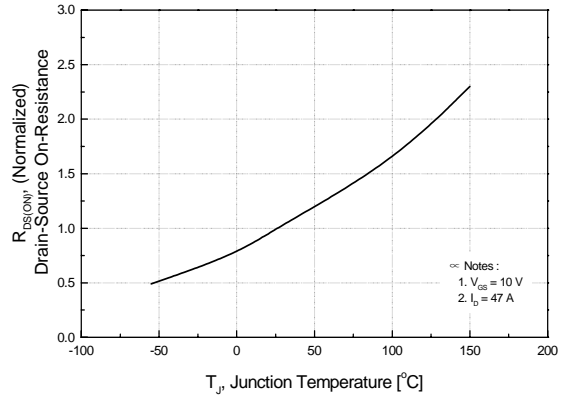


Figure 9. Safe Operating Area

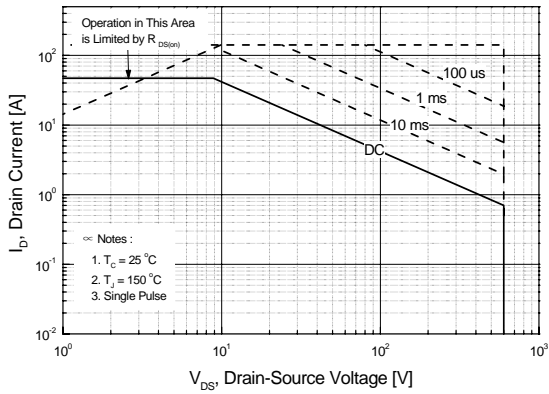


Figure 10. Maximum Drain Current vs. Case Temperature

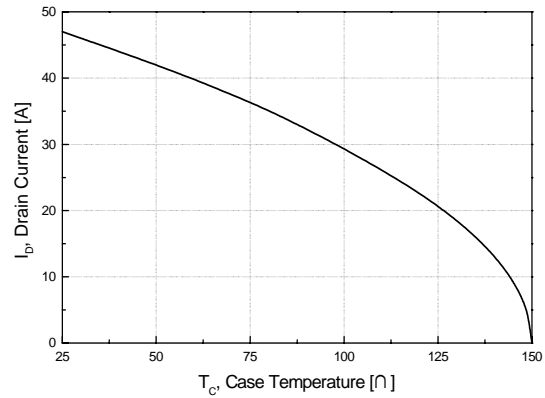
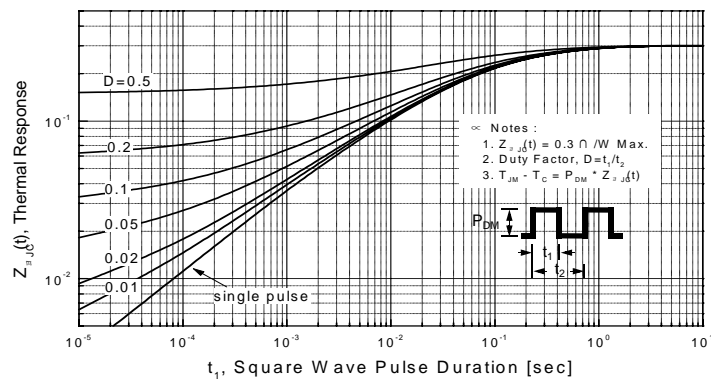
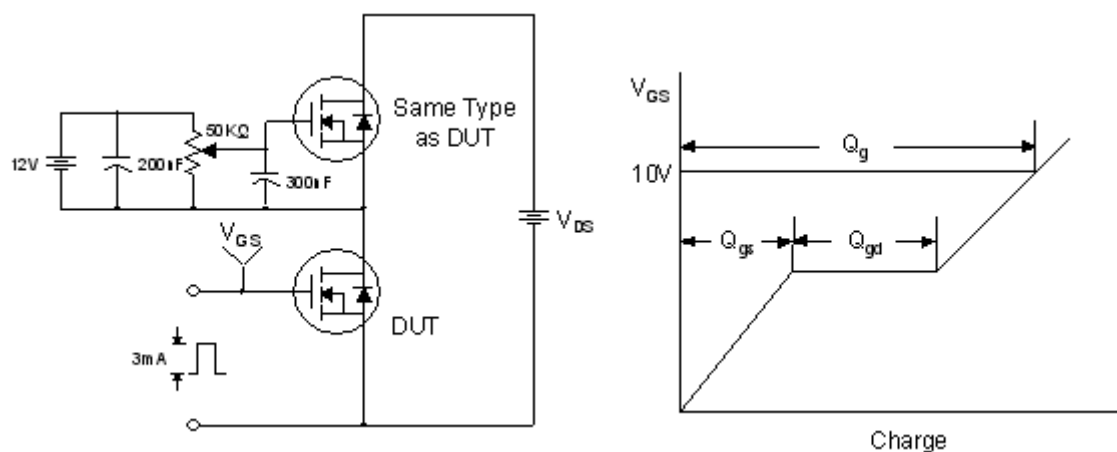


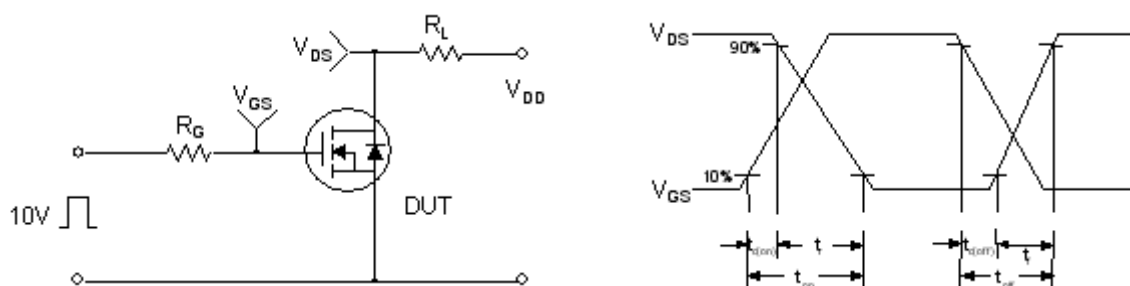
Figure 10. Transient Thermal Response Curve



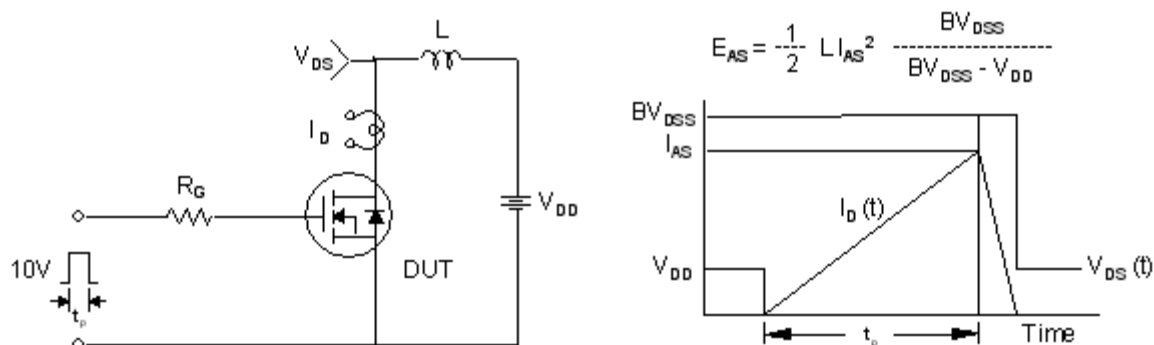
Gate Charge Test Circuit & Waveform

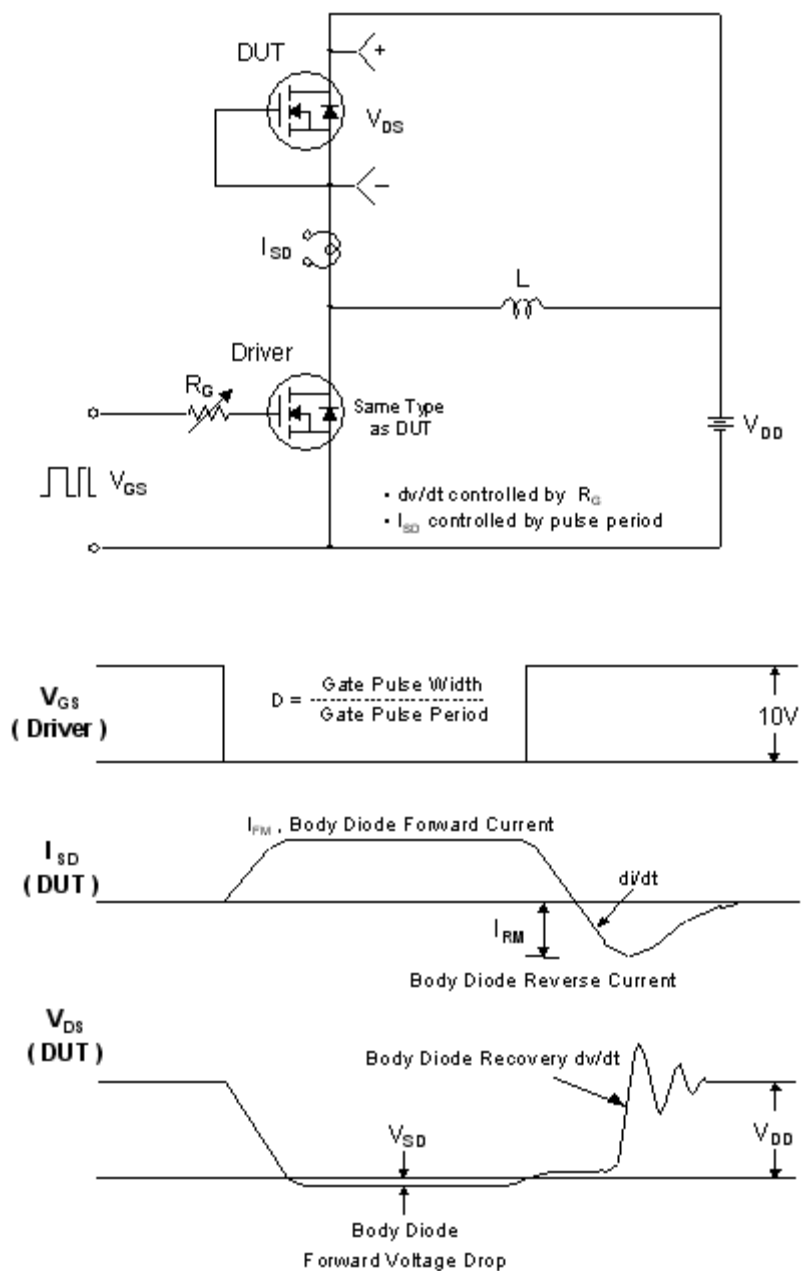


Resistive Switching Test Circuit & Waveforms



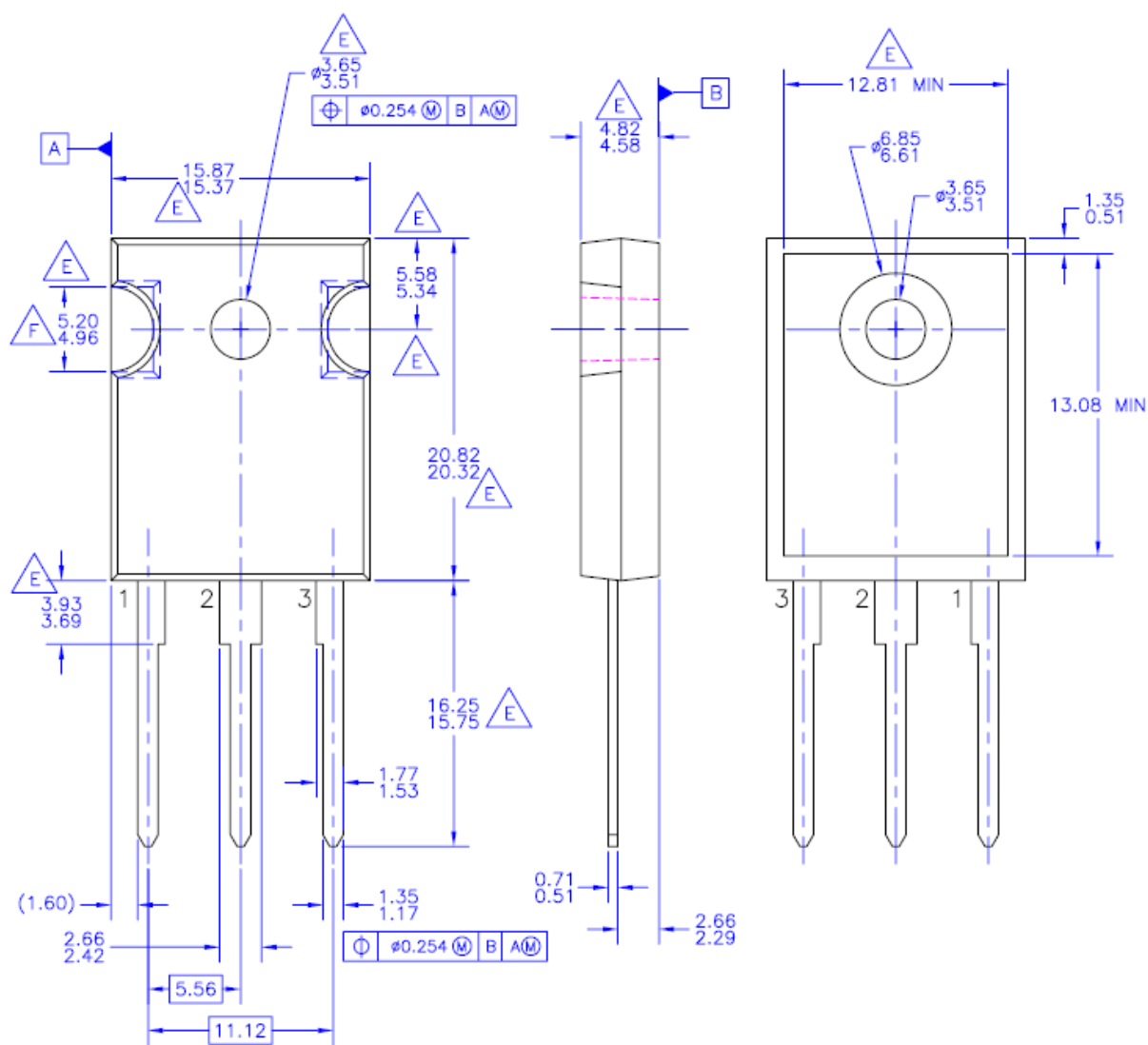
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

TO-247AB



Dimensions in Millimeters

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